Power Transistors Panasonic

2SC5517

Silicon NPN triple diffusion mesa type

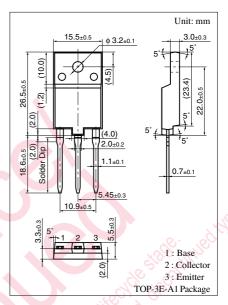
For horizontal deflection output

■ Features

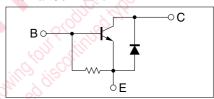
- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide area of safe operation (ASO)

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter		Symbol	Rating	Unit	
Collector to base voltage		V _{CBO}	1 700	V	
Collector to emitter voltage		V _{CES}	1 700	V	
Emitter to base voltage		V _{EBO}	7	V	
Peak collector current		I _{CP}	12	A	
Collector current		I_{C}	6	A	
Base current		I_{B}	3	A	
Collector power	$T_C = 25^{\circ}C$	P _C	40	W	
dissipation	$T_a = 25^{\circ}C$		3		
Junction temperature		T _j	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



Internal Connection

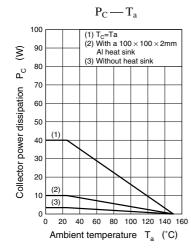


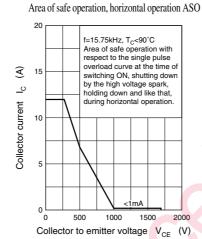
■ Electrical Characteristics $T_C = 25$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 1\ 000\ V,\ I_E = 0$			50	μΑ
		$V_{CB} = 1700 \text{ V}, I_{E} = 0$			1	mA
Emitter to base voltage	V_{EBO}	$I_{\rm E} = 500 \text{ mA}, I_{\rm C} = 0$	7			V
Forward current transfer ratio	h _{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 4.5 \text{ A}$	5		9	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 4.5 \text{ A}, I_B = 0.9 \text{ A}$			5	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = 4.5 \text{ A}, I_B = 0.9 \text{ A}$			1.5	V
Transition frequency	f_{T}	$V_{CE} = 10 \text{ V}, I_{C} = 0.1 \text{ A}, f = 0.5 \text{ MHz}$		3		MHz
Storage time	t _{stg}	$I_C = 4.5 \text{ A}, I_{B1} = 0.9 \text{ A}, I_{B2} = -1.8 \text{ A}$			5.0	μs
Fall time	t _f				0.5	μs
Diode forward voltage	V_F	$I_F = 4.5 \text{ A}$			-2	V

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